

Title (en)

AN INTEGRATED HOLLOW COPPER ELECTRODE IN SLAG HOLE WITH THERMAL CONDUCTIVITY

Title (de)

INTEGRIERTE HOHLE KUPFERELEKTRODE IN EINEM SCHLACKENLOCH MIT THERMISCHER LEITFÄHIGKEIT

Title (fr)

ÉLECTRODE EN CUIVRE CREUSE INTÉGRÉE DANS UN TROU À LAITIER À CONDUCTIVITÉ THERMIQUE

Publication

EP 3994958 A4 20221026 (EN)

Application

EP 21786314 A 20210131

Priority

- IR 13993005776 A 20200926
- IB 2021050756 W 20210131

Abstract (en)

[origin: WO2022064280A1] In order to extend the service life of electrode in the slag hole, a single copper electrode has been used in this invention. The special design of this part in resistance to thermal stresses makes it safe as a protective part against temperature of 1200 C. The heat generated in the body of this part is expelled from the part through the circulating fluid through the designed ducts and the temperature of the part remains constant to the extent that it does not cause damage to the part. The heat generated in the body of this part is expelled from the part through the circulating fluid through the designed ducts and the temperature of the part remains constant to the extent that it does not cause the destruction of the part.

IPC 8 full level

H05B 7/10 (2006.01); **B23K 9/24** (2006.01); **B23K 35/00** (2006.01); **C21B 7/14** (2006.01); **H05B 7/06** (2006.01)

CPC (source: EP)

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C21C 2005/5235 (2013.01); **C21C 2250/06** (2013.01)

Citation (search report)

- [I] WO 2019224613 A1 20191128 - MIWENTI S R L [IT]
- [AD] CN 103468845 A 20131225 - NANJING UNITED RONGDA ENGINEERING MATERIAL CO LTD
- [A] JP S5397645 A 19780826 - DAIDO STEEL CO LTD
- See references of WO 2022064280A1

Designated contracting state (EPC)

AL AT BE BG CH CY CZ DE DK EE ES FI FR GB GR HR HU IE IS IT LI LT LU LV MC MK MT NL NO PL PT RO RS SE SI SK SM TR

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DOCDB simple family (publication)

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